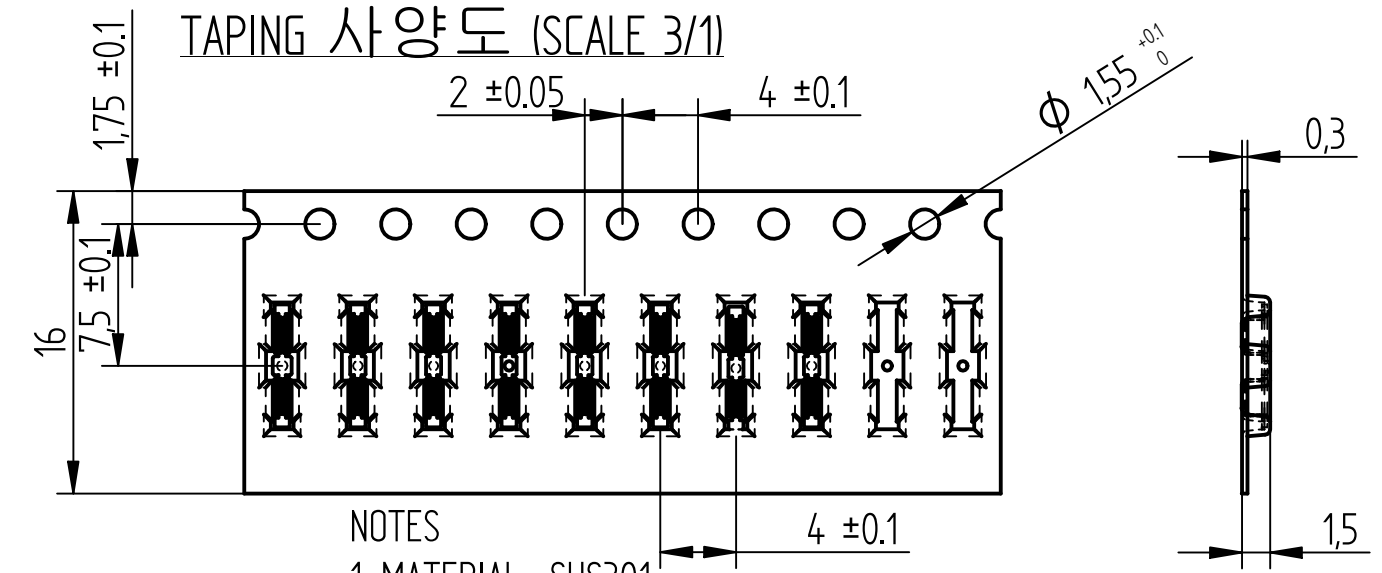
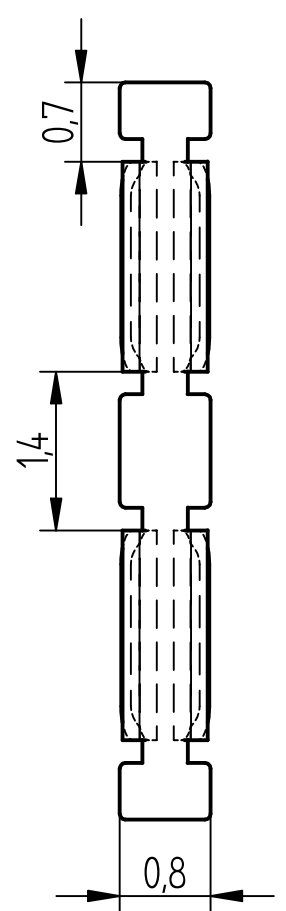
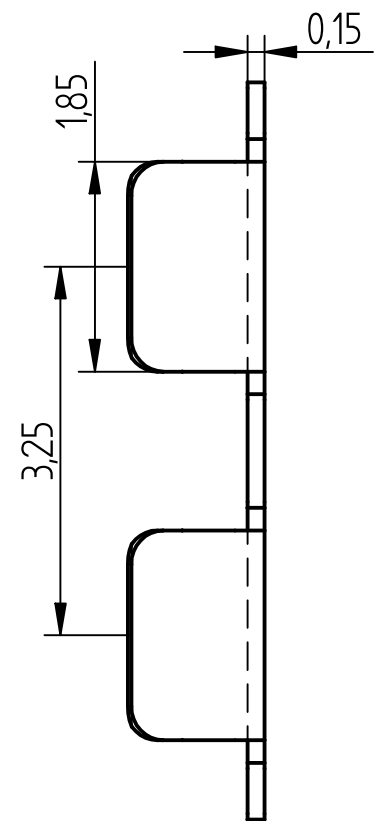
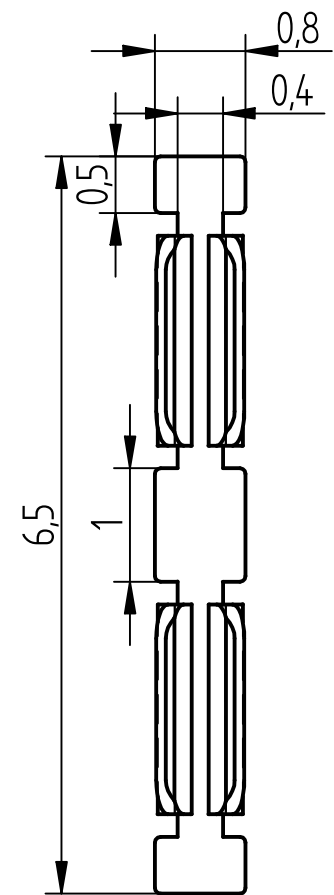


REVISION HISTORY

REV	DESCRIPTION	DATE	APPROVED
A	신규 제정	2009.10.05	P.K.KO
B	인입부 공차 수정 +0.1 -0.05	2012.02.15	P.K.KO
C	SHIELD CASE THICKNESS 0.2±0.02 => 0.2 +0.02 -0	2012.03.30	P.K.KOH

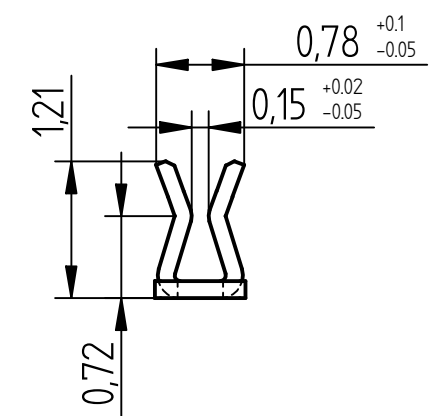


NOTES

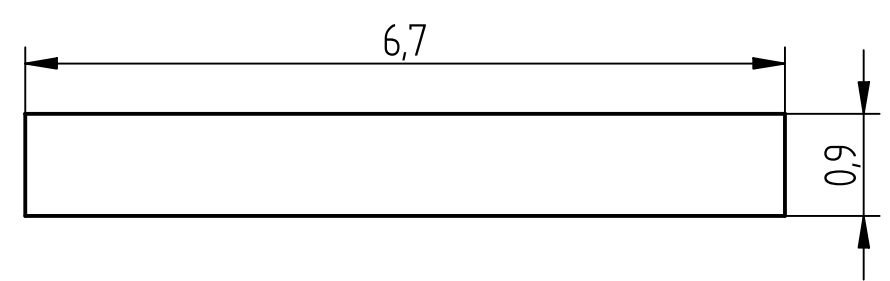
1. MATERIAL : SUS301
2. MATERIAL THICKNESS : 0.15t
3. FINISHED : Sn(100%) PLATING ON BOTH SIDE  
( Ni 0.5µm Sn1.27µm )
4. PACKING MATERIALS.  
- REEL : HIPS 0.3t  
- COVER TAPE : PS  
- Q'TY/REEL : 10,000ea
5. AVAILABLE SHIELD CASE THICKNESS : 0.2 +0.02 -0
6. CONTACT RESISTANCE 300mmΩ MAX
7. INTENTION FORCE/RETENTION FORCE SPEC

	INTENTION FORCE	RETENTION FORCE
SPEC	MAX 1.0Kg	MIN 0.3Kg

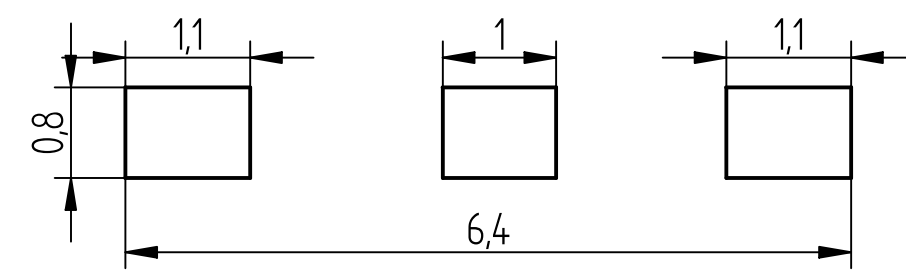
8. STENCIL THICKNESS : 0.12T
9. Maintain 90°±3 while engage & disengage shield can & shield clip to prevent deformation & to maintain retention force of shield clip



SCALE : 15/1



RECOMMENDED PCB LAYOUT



RECOMMENDED STENCIL LAY-OUT 0.1T

UNLESS OTHERWISE SPECIFIED  
DIMENSIONS ARE IN MILLIMETERS  
TOLERANCES ARE  
ANGLES ± 0.3°  
0 ~ 1 ± 0.05  
1 ~ 5 ± 0.1  
5 ~ 10 ± 0.15

TITLE SHILED CLIP		
SIZE A3	DWG NO ICSRC6508SFR	REV C
FILE NAME: ICSRC6508SFR.dft		
SCALE:	WEIGHT:	SHEET 1 OF 1